

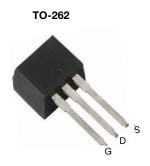
# IPI04CN10N G-VB Datasheet N-Channel 100 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (A)				
100	0.004 at V <sub>GS</sub> = 10 V	110 <sup>a</sup>				

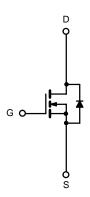
#### **FEATURES**

- Trench Power MOSFET
- New Package with Low Thermal Resistance
- 100 % R<sub>g</sub> Tested









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>C</sub> = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	100				
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Danie Comment /T 475 °C)	T <sub>C</sub> = 25 °C		110 <sup>a</sup>	A		
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	87 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	440	A			
Avalanche Current	I <sub>AR</sub>	75				
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	280	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	В	375 <sup>c</sup>	W		
waximum Fower Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.75			
Operating Junction and Storage Temperatu	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Limit	Unit			
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W			
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.4	C/VV				

#### Notes:

- a. Package limited.
- b. Duty cycle ≤ 1 %.
- c. See SOA curve for voltage derating.
  d. When mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250  \mu\text{A}$	100			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.004			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.017		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.025			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			6700		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		750			
Reverse Transfer Capacitance	C <sub>rss</sub>			280			
Total Gate Charge <sup>c</sup>	Qg			110	160	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		24			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			24			
Gate Resistance	$R_{g}$		1.0		6.2	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	30		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		125	200	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85		
Fall Time <sup>c</sup>	t <sub>f</sub>			130	195		
Source-Drain Diode Ratings and Ch	aracteristics -	Γ <sub>C</sub> = 25 °C <sup>b</sup>		•			
Continuous Current	I <sub>S</sub>				110	A	
Pulsed Current	I <sub>SM</sub>				240		
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			70	140	ns	
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dl/dt = 100 A/μs		5.5	10	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.19	0.35	μC	

#### Notes:

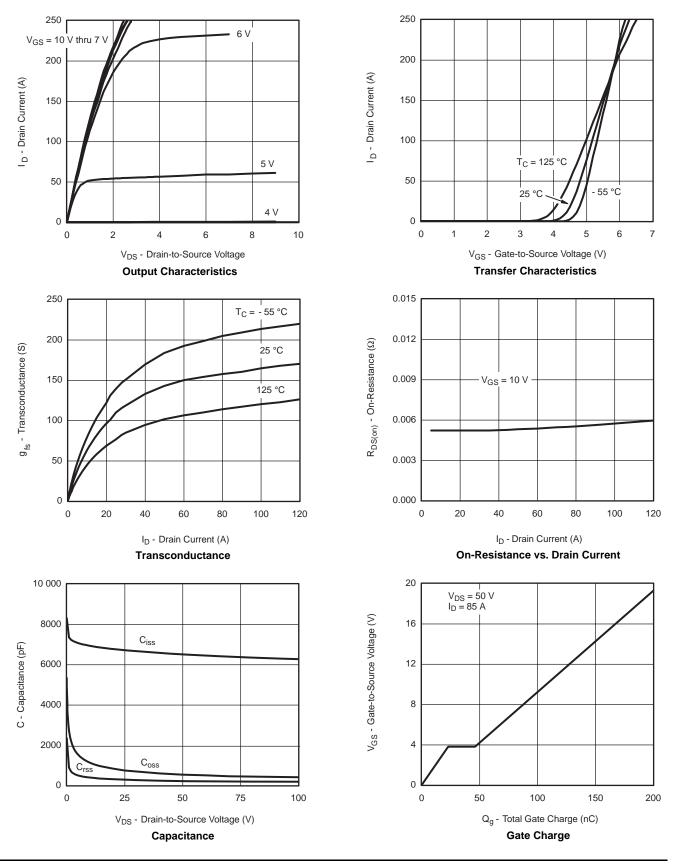
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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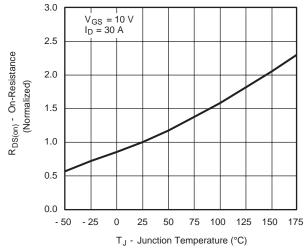
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



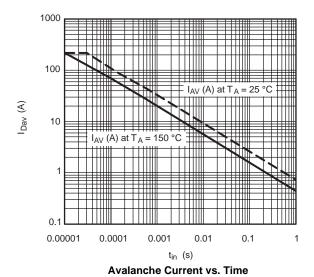
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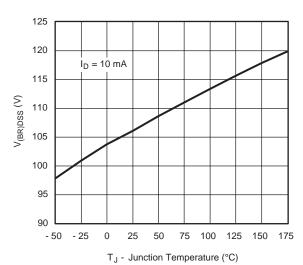


#### On-Resistance vs. Junction Temperature



T<sub>J</sub> = 150 °C T<sub>J</sub> = 25 °C T<sub>J</sub>

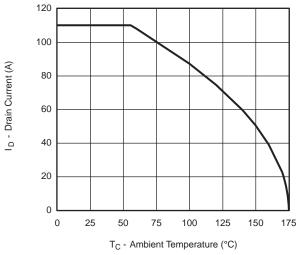
Source-Drain Diode Forward Voltage



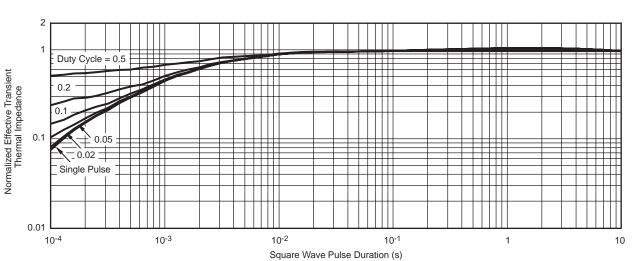
Drain Source Breakdown vs. Junction Temperature



#### THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



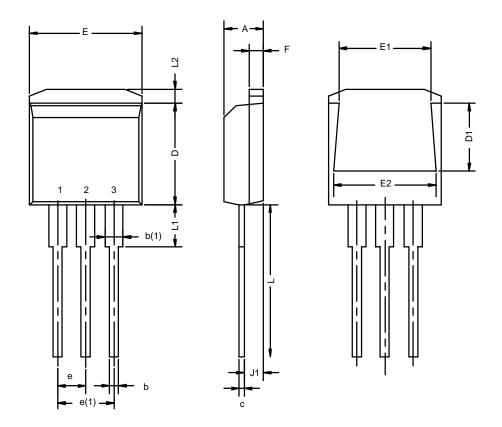
Normalized Thermal Transient Impedance, Junction-to-Case

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### TO-262: 3-LEAD



	MILLIMETERS* INCHES			HES	
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
Е	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

<sup>\*</sup>Use millimeters as the primary measurement

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